



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TO-247AC (HVM)					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
Bond int.	120	60 000	200 °C + N2	0	0.00
HAST	1098	144 400	130 °C, 85 % RH	0	0.00
Pressure pot	1068	121 728	121°, 15 PSIG	0	0.00
Temp. cycle	1150	1 520 000	-55 °C to +150 °C	0	0.00
Solderability	75	750	883 M2003	0	0.00
Power cycle	486	3 573 280	Delta T _J = 100 °C	0	0.00
Solder dunk	247	32 916	260 °C, 10 s	0	0.00